

Applicant : Ewald Karl Michael Guenther, Zhong
Chen and Brian Cotterell
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Amendments to the Specification:

Please replace the abstract with the following amended abstract:

A¹ A method of fabricating a device, ~~comprising~~ including mechanically patterning a device layer using a stamp containing ~~the~~ a desired pattern. The device layer is formed on a plastic or polymeric substrate. The stamp is pressed against the substrate under a load which patterns the device layer without cracking ~~it~~ the device layer in the non-patterned areas.